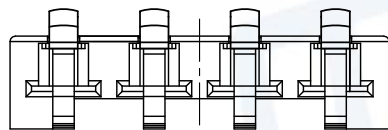


SECTION A-A



TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 11.80LX10.62WXH mm
H=2.60 mm
Durability: 5,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical, 100mΩ max
Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vaporphase: 215°C, 30sec.Max
IR reflow: 250°C, 5sec.Max
Manual soldering: 370°C, 3sec.Max

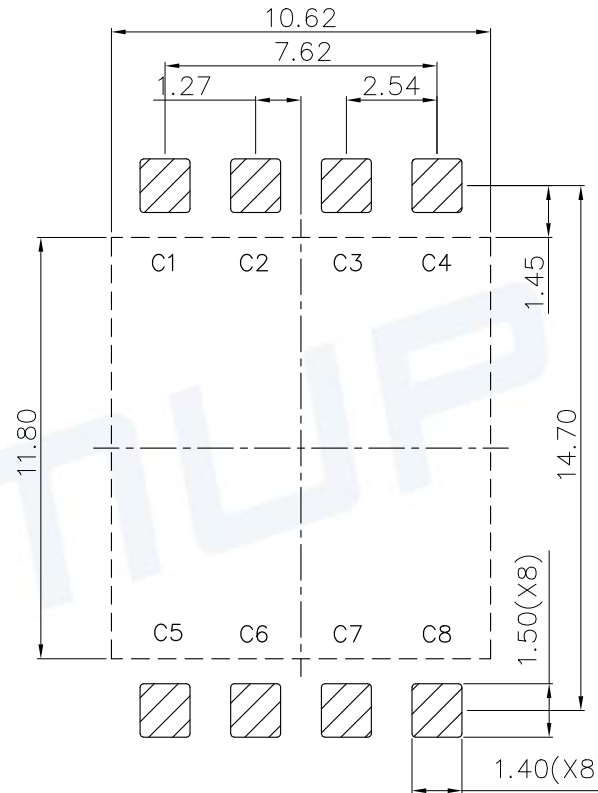
4.Environmental Characteristics

Operating temperature: -40°C~+85°C
Operating humidity: 10%~+95%RH

SIM CARD

| Pin No. | NAME |
|---------|----------|
| C1 | VCC |
| C2 | RST |
| C3 | CLK |
| C4 | Reserved |
| C5 | GND |
| C6 | VPP |
| C7 | I/O |
| C8 | Reserved |

| REV. | DESCRIPTION OF REVISIONS | APPR. | CHKD. | DRAW. | DATE |
|------|--------------------------|-------|-------|-------|------------|
| ▲ | NEW | | | Zoey | 2009/12/7 |
| ▲ | Original Model C733-3 | | | HXR | 2023/10/24 |



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

| ITEM | PART NAME | Q'TY | MATERIAL | FINISH |
|------|--------------|------|-----------------------|--------------------------|
| 1 | HOUSING | 1 | Hi-temp Thermoplastic | Black UL94V-0 |
| 2 | DATA CONTACT | 8 | Copper Alloy | Contact area:Gold plated |

Unless otherwise specified, other tolerance are:

| | | | |
|-------|-------|--------|-----|
| X | ±0.35 | X* | ±5* |
| X.X | ±0.25 | X.X* | ±4* |
| X.XX | ±0.15 | X.XX* | ±3* |
| X.XXX | ±0.10 | X.XXX* | ±2* |

PROJ. UNIT mm SCALE 1:1

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**
MODEL NO: **MUP-C7033-03**
TYPE: **H2.6 without post 8p**

| | | | |
|----------|-------------------|----------|-----------------|
| DRAWN | Zoey Dec.07.2009 | DWG NO.: | DWG-C7033-03-01 |
| CHECKED | Jimmy Dec.07.2009 | SHEET | 1/1 |
| APPROVAL | Jun Dec.07.2009 | REVISION | 2 |

